

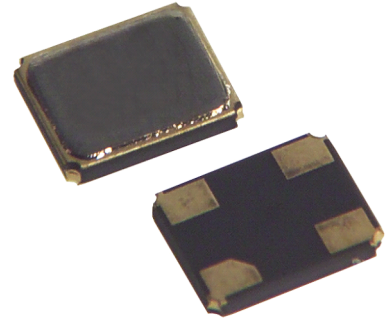
# Series TX3

## SEAM SEALED CERAMIC 3.2 X 2.5mm SMD



### FEATURE

- Ultra thin, thickness 1.0mm
- Leadless type
- High precision characteristic covering up to high frequency range
- Designed for automatic mounting and reflow soldering
- Emboss taping specification
- The best choice of Bluetooth wireless communication sets, DSN, PDA and mobile phone.



### ELECTRICAL SPECIFICATIONS

Output Frequency Range	12.000 MHz to 48.000 MHz
Mode	see Table 1*
Frequency Tolerance (at 25°C)	±10ppm, ±30ppm or specify
Frequency Stability Over Operating Temperature Characteristics	±10ppm, ±30ppm or specify
Operating Temperature Range	-10 °C to +60 °C -20 °C to +70 °C -40 °C to +85 °C
Storage Temperature Range	-55 °C to + 125 °C
Shunt Capacitance (C <sub>0</sub> )	5.0 pF Max
Driver Level (Typical)	10μW~100μW
Load Capacitance(C <sub>L</sub> )	Series, 16pF, 20pF, 30pF, 32pF, or specify
Aging @25°C 1 <sup>st</sup> year (Max)	±3ppm/year
Shock Resistance	Drop test of 3 times on 2mm stainless plate from 75cm height

**REMARK:** SPECIFICATIONS SUBJECT TO CHANGE WITHOUT PRIOR NOTICE. PLEASE CONFIRM WITH OUR SALES ENGINEER.

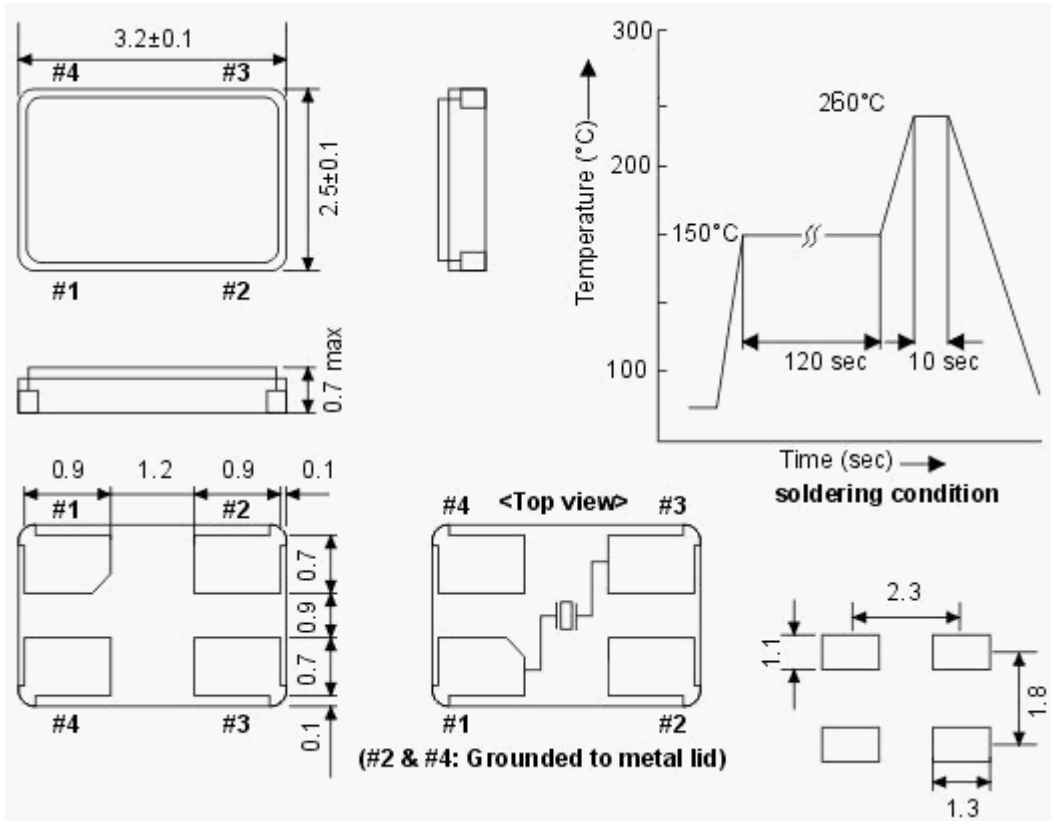
### EQUIVALENT SERIES RESISTANCE ( ESR) (Table 1)

Frequency Range	E.S.R(Ω)	Mode
12~24MHz	80 Ω Max	AT/Fundamental
24~50MHz	60 Ω Max	AT/Fundamental

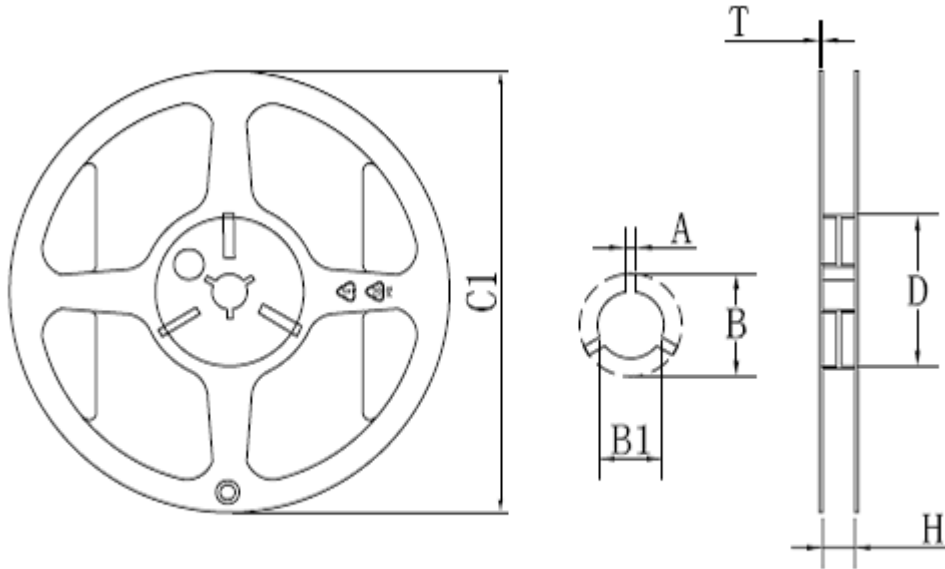
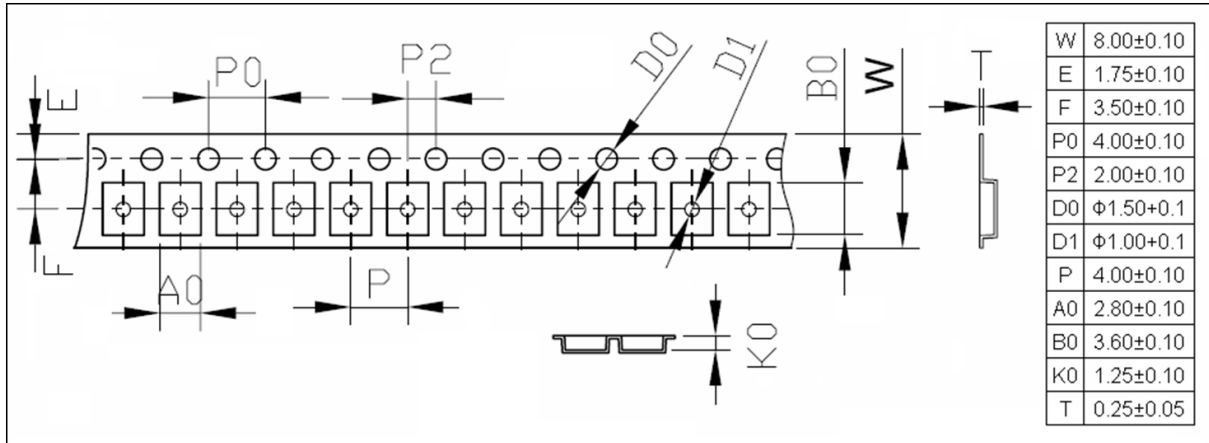
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## SEAM SEALED CERAMIC 3.2 X 2.5mm SMD

### Dimension



**Series TX3**  
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**Type & Reel**



$C1 \pm 1$	$A \pm 0.3$	$B \pm 0.3$	$B_1 \pm 0.3$	$T \pm 0.2$	$D \pm 0.5$	$H_{-0.5}^{+0.5}$
178	2.5	21.0	13.2	1.0	60.5	8.5